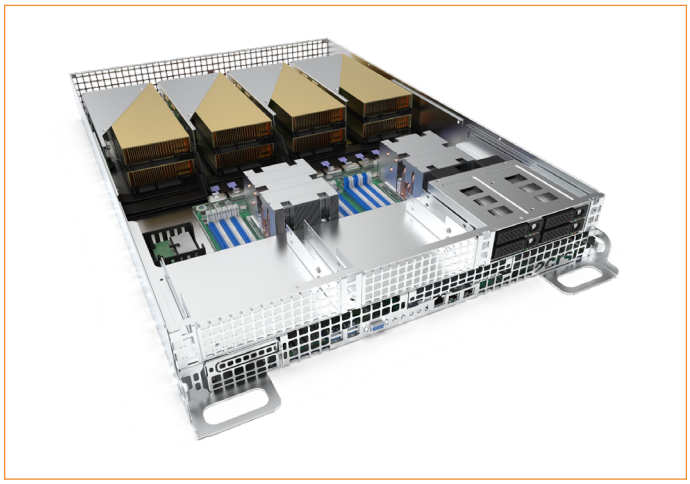
DATASHEET

OCtoPus 1.8GG

OCP READY IMMERSION COOLING SERVER

2 OpenU / 8 GPUs



No contractual

Key Features per node

- 21-inch 2OpenU
- Dual AMD EPYC™ 9004-9005 Socket SP5
- 24x DDR5 @ 4800MHz
- 8x PCIe 5.0 x16 for GPUs
  1x PCIe 5.0 x16, HH-HL
  1x PCIe 5.0 x16, HH-HL
- Immersion cooling

High-Performance Computing, Designed for Immersion Cooling

Engineered for advanced immersion cooling solutions, our 2U server offers unparalleled flexibility and power in a compact form factor.
Key features include support for up to 8 GPUs, each with a maximum power draw of 600W, and dual AMD EPYC™ processors from the 9004/9005 series families.
Say goodbye to overheating limits and hello to ultimate performance.

OCP ORV3 Compliance

This server is OCP ORV3-compliant, ensuring compatibility with open compute infrastructure standards, and incorporates optional front I/O configurations for enhanced modularity. It supports seamless integration into cutting-edge immersion cooling environments, maintaining peak performance while reducing thermal constraints.

Unmatched Scalability and Flexibility

With its versatile architecture, this server accommodates a wide range of configurations to meet diverse operational needs. From high-density GPU setups to mixed workloads, it adapts seamlessly to support varying computational demands, making it an ideal choice for growing businesses and large-scale deployments alike.

Optimized for Next-Gen Workloads

Designed to excel in AI workloads, HPC clusters, and enterprise environments, this solution delivers unmatched efficiency, reliability, and scalability for even the most demanding computational tasks.

SCAN THE CODE!
TO DISCOVER MORE
ABOUT THIS PRODUCT

2crsi.com | contact@2crsi.com

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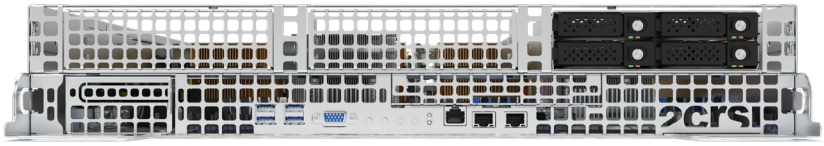


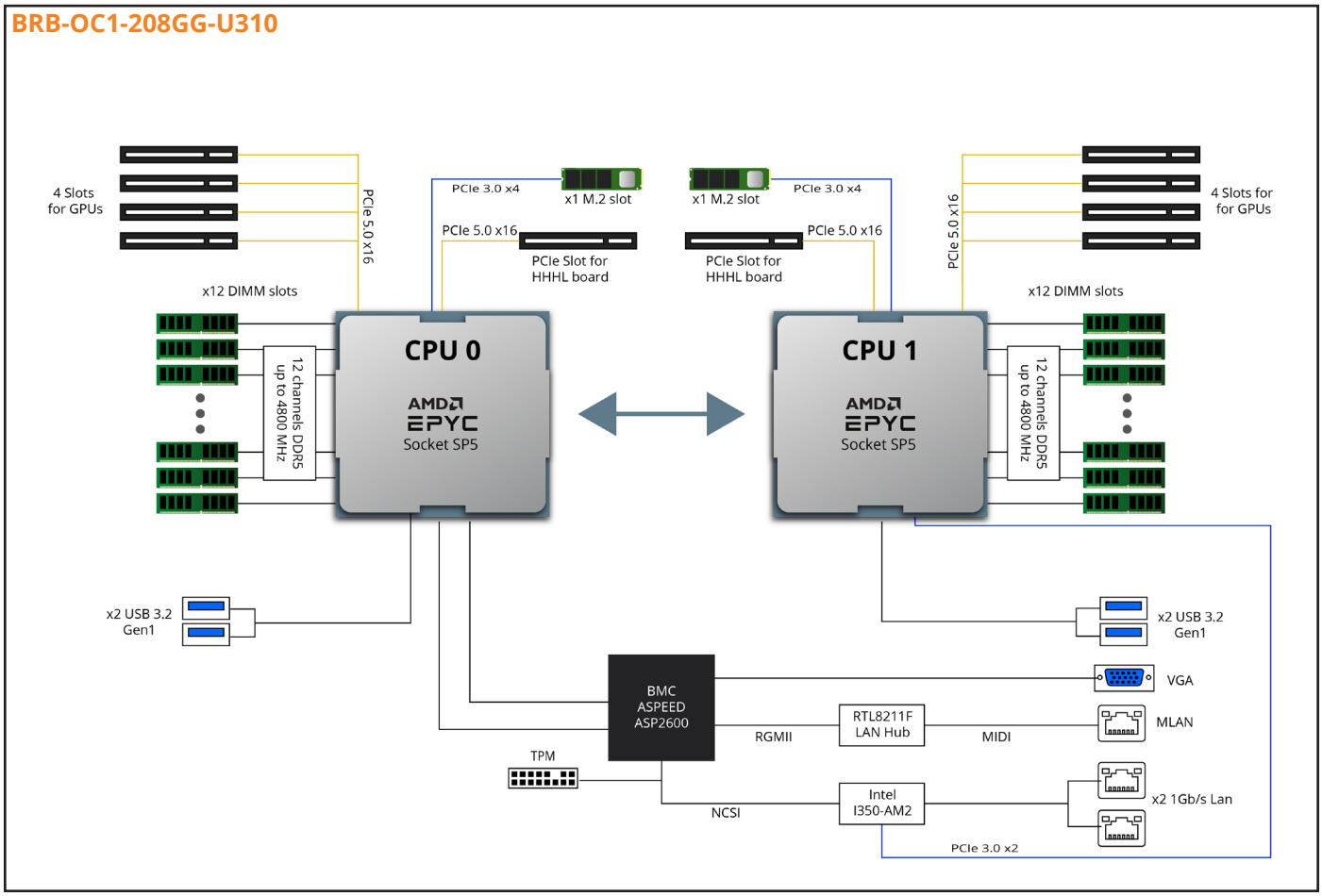
SKU based on options

This product is available with different options.
This table provides valuable information about the features and capabilities associated with each SKU (stock keeping unit), enabling potential customers and internal stakeholders to make informed decisions. Each SKU has been carefully classified according to the options available, providing a clear picture of the functionality associated with each variant.

SKU	Front storage	Hotswap	Spec
BRB-OC1-208GG-U310	No	NA	8x PCIe 5.0 x16 for Dual slot GPUs cards (Front) 2x PCIe 5.0 x16 for HH-HL cards (Front) 2x M.2 NVMe PCIe 5.0 x2 2280/22110 (internal) 1x OCP3.0 PCIe 5.0x16 (front)
BRB-OC1-208GG-U311	4x 15mm 2.5" NVMe bays	Yes	8x PCIe 5.0 x16 for Dual slot GPUs cards (Front) 1x PCIe 5.0 x16 for HH-HL cards (Front) 2x M.2 NVMe PCIe 5.0 x2 2280/22110 (internal) 4x 15 mm Sata/SAS hot-swappable bays
BRB-OC1-208GG-U312	2x 15mm 2.5" NVMe bays	No	8x PCIe 5.0 x16 for Dual slot GPUs cards (Front) 2x PCIe 5.0 x16 for HH-HL cards (Front) 2x M.2 NVMe PCIe 5.0 x2 2280/22110 (internal) 1x OCP3.0 PCIe 5.0x16 (front)

BLOCS DIAGRAMS

BRB-OC1-208GG-U310



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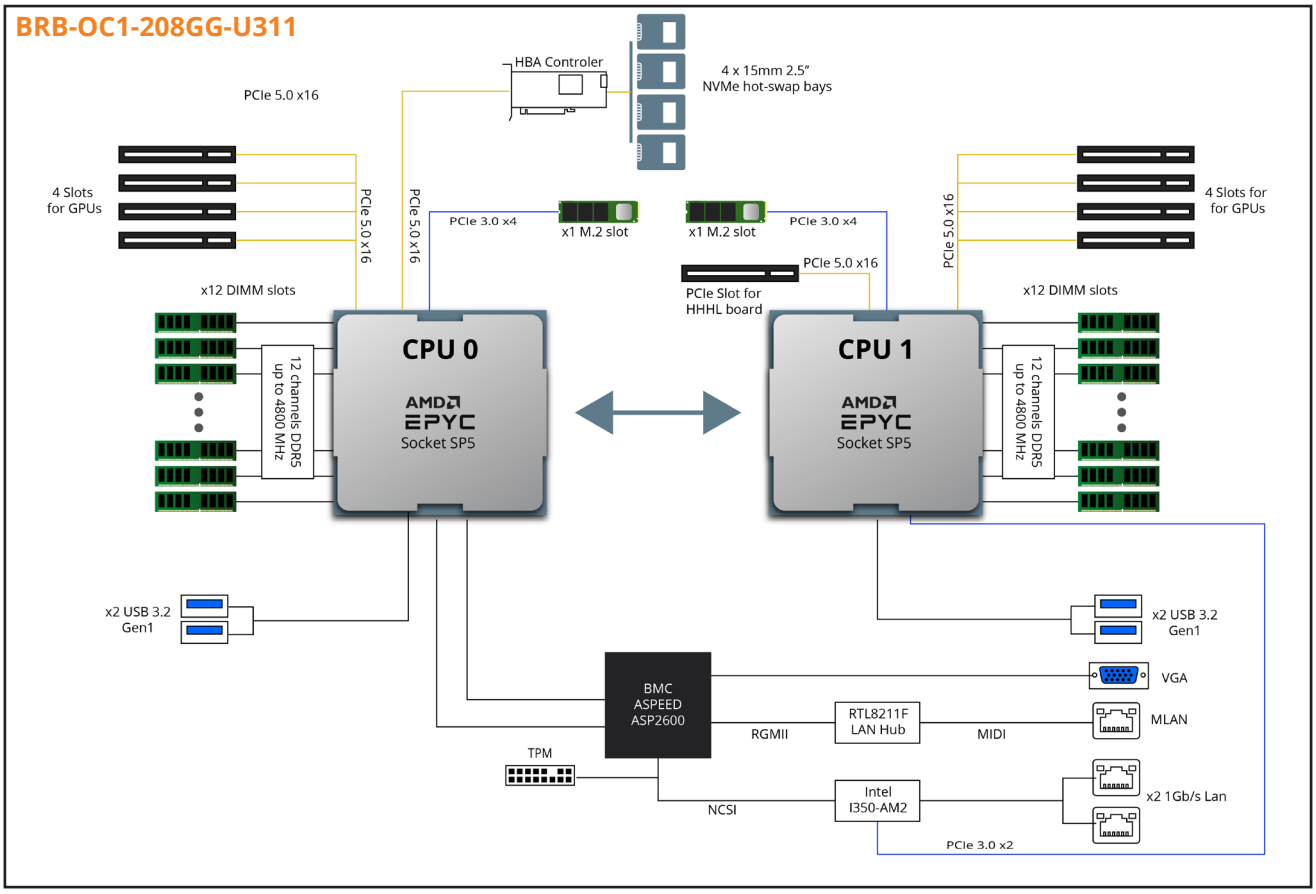
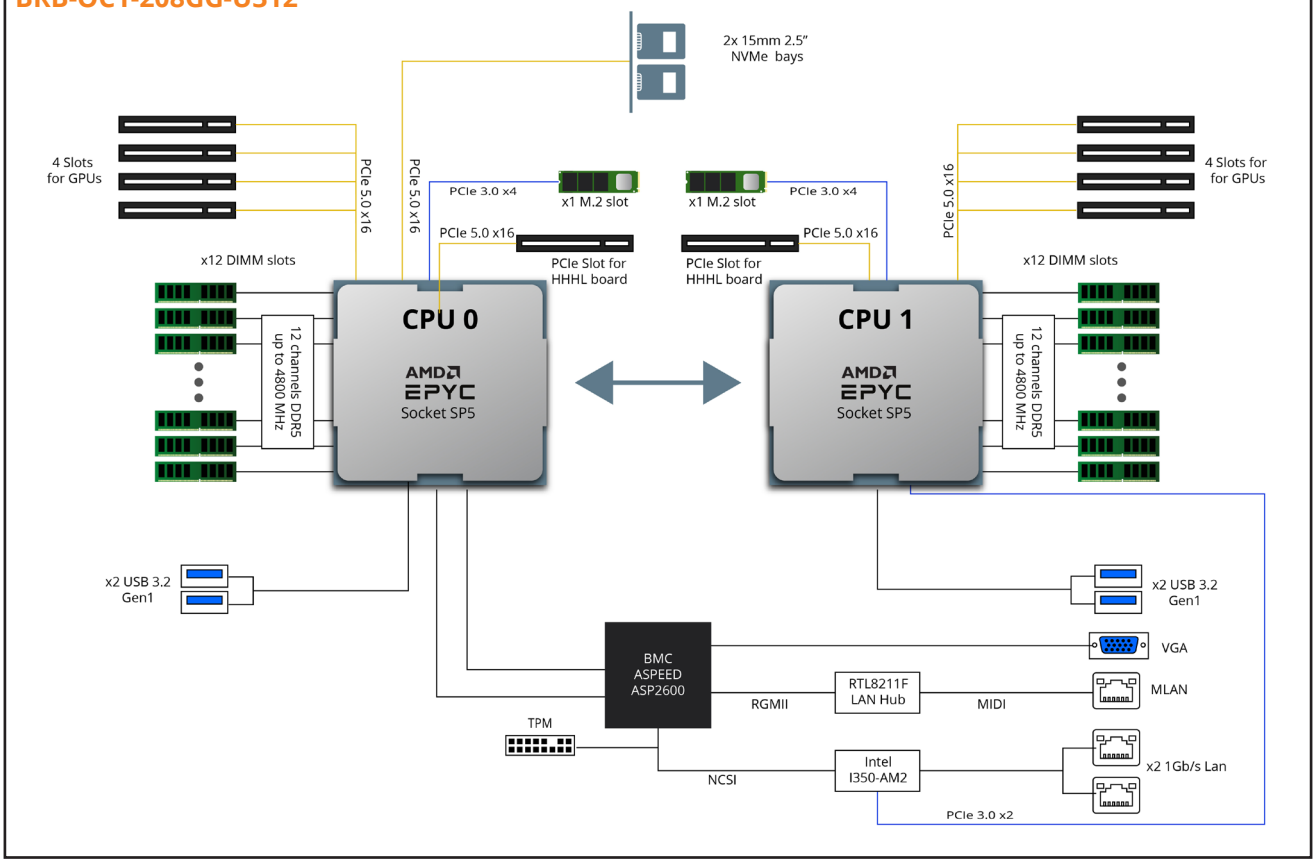
BRB-OC1-208GG-U311



BRB-OC1-208GG-U312



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SPECIFICIATIONS

system	**Model**	OCtoPus 1.8GG
	Form factor	21-inch 2OpenU
	Dimension	880 x 537 x 86mm (D x W x H)
	Cooling technology	Immersion Cooling One phase
Storage	**Internal type per node**	1x M.2 (Gen3 x4 link, PCIe or SATA 6Gb/s); Form factor: 22110/2280 [CPU0] 1x M.2 (Gen3 x4 link, PCIe or SATA 6Gb/s); Form factor: 22110/2280 [CPU1]
	External type per node	Options: 4x 15mm 2.5" NVMe hot-swappable bays 2x 15mm 2.5" NVMe bays
	RAID controler	MegaRAID 9660-16i (Gen4) Tri-Mode RAID Adapter (Optional)
Motherboard	**CPU per node**	Dual socket SP5 AMD EPYC™ 9XX4/9XX5* Genoa, Turin, Bergamo and Genoa X with AMD 3V V-Cache™ Technology Series Processor Families cTDP up to 400W *10.01 BIOS version and 10.02 BMC update are required to support AMD EPYC™ 9005 series processors
	Chipset	System on chip
	Expansion slots per node	4x PCIe x16 (Gen5 x16 link), FH-FL DW [CPU0]* 4x PCIe x16 (Gen5 x16 link), FH-FL DW [CPU1] * *For GPU TDP up to 600W, NVL2 supported 1x PCIe x16(Gen5 x8 link), HH-HL [CPU0] 1x PCIe x16 (Gen5 x16 link), HH-HL [CPU1]
	TPM per node	1x TPM header with SPI interface for TPM 2.0 module optional
	BMC	Aspeed 2600
Memory	**Total slots per node**	24 DIMM slots (12-Channel per CPU, 12 DIMM per CPU)
	Total Capacity per node	RDIMM modules up to 96GB supported 3DS RDIMM modules up to 256GB supported
	Memory type and speed	RIMM DDR5 4800 MHz (1DPC) / 4000MHz (2DPC) RDIMM-3DS DDR5 4400 MHz (1DPC) / 3600MHz (2DPC)
Network	**Onboard**	1x Realtek RTL8211E for dedicated management GLAN 2x 1GbE LAN ports (1 x Intel® i350-AM2), support NCSI
I/O	**Front**	4x USB 3.2 Gen1 type A 1x DB15 (VGA) 2x RJ45 1x RJ45 Management port
	Switch / LED	1x Power button with LED 1x ID button with LED 1x HDD LED 1x Status LED 1x System reset button
Management solution	**Software**	Aspeed® AST2600 management controller
	Remote management	BMC Remote control based on Aspeed® AST2600 remote management controller. (Power Control Configuration, Chassis Identify, Boot Option, iKVM, BMC Account Configuration)
Power supply	**Type**	OCP technology ORV3 48V DC
Operating environement	**Operating temperature**	10°C ~ 35°C (50°F ~ 95°F)
	Non-operating temperature	Non operation temperature: -40°C ~ 60°C (40° ~ 140°F)
	Operative relative humidity	95%, non-condensing at 35° C
Warranty	**2CRSi** hardware warranty includes a one year, parts and labour with return to 2CRSi selling entity. Customers may purchase an extended warranty of up to 3 years on parts and labour with different support levels. Please contact 2CRSi at support@2crsi.com or reach your sales point of contact for complete warranty details including limitations and transferability. 2crsi.com/global-location	